Rev Date: 14/07/2023



LOW OHM POWER RESISTORS

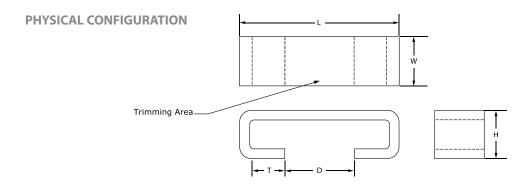
HOS SERIES Size 4512/4524

• Open frame strip type. • 2W to 5W. • R001 to R05.



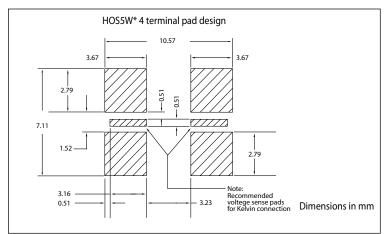




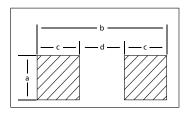




Recommended PCB layout for high precision applications: Kelvin (4 terminal pad design) is suggested as per illustration below. The high current connections are made to the two pairs of larger pads and the voltage sense connections are made to the two smaller central pads.



Recommended PCB layout for normal application



DIMENSIONAL TABLE

Sr No.	HTRTYPE		H (MM)		D ±	W ±	ʻa' NOM	ʻb' NOM		'd' NOM	Typical weight per piece (Gms) Based on Resistance value			Size
				0.25 (MM)	0.8 (MM)	0.40 (MM)					Low	Med	High	
1	HOS2W* > R003 T to R05	11.20 ± 0.40	3.05 ±0.80	2.63	4.83	3.2	4.07	9.37	3.07	3.23	0.45	0.25	0.05	4512
2	HOS3W* > R003 T to R05	11.20 ± 0.40	3.05 ±0.80	2.63	4.83	3.2	4.07	9.37	3.07	3.23	0.45	0.25	0.05	4512
3	HOS2W* / HOS3W* R003	11.20 ± 0.40	3.51 ±0.80	2.63	4.83	3.2	4.07	9.37	3.07	3.23		0.45 Approx	X	4512
4	HOS2W* / HOS3W* R002	11.60 ± 0.40	3.51 ±0.80	2.63	4.7	3.6	4.45	9.37	3.07	3.23		0.50 Approx	X	4512
5	HOS5W* R001 T to R025		2.28 to 4.57©	2.63	4.83	6.01 ± 0.38	7.24	9.58	3.18	3.23	0.55	0.35	0.13	4524

APPLICATIONS

- · Current sensor for power hybrid applications
- In the automotive sector for high current applications
- Where reduced temperature is required on PCB

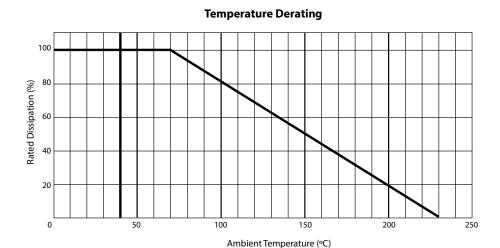
FEATURES

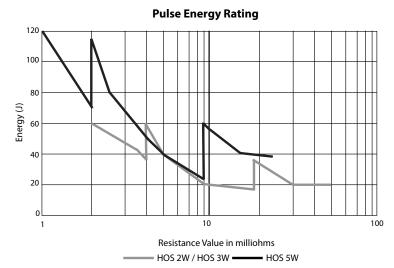
- Reduced PCB heating due to open air flow design as compared to flat chip format.
- Flexible nature of termination design for thermal expansions.

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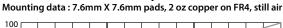
POWER
RESISTORS
HOS
Size 4512/4524

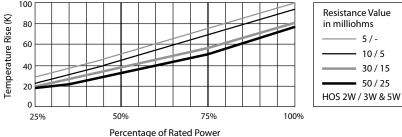




NOTE : This graph relates to single pulses of short duration (≤ 100ms). Higher energy limits apply for longer pulses and overloads.

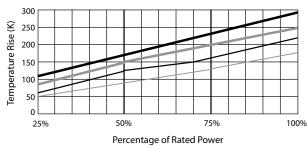
Solder Joint Temperature Rise

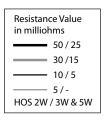




Hot Spot Temperature Rise

Mounting data: 7.6mm X 7.6mm pads, 2 oz copper on FR4, still air





Note:

Temperature rise data are given here for typical mounting conditions. Actual figures depend on PCB copper weight, mounting pad size, track width and substrate type. Also, the open air format responds better to forced air cooling than chip format resistors. For values below 5 milliohms allowance should be made for heat generated in the copper tracks themselves. Application-specific guidance is available on request from our application laboratory.

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POWER RESISTORS

Size 4512/4524

ELECTRICAL AND ENVIRONMENTAL CHARACTERISTICS

PARAMETER / PERFORMANCE TEST & TEST METHOD	PERFORMANCE REQUIREMENTS
Power Rating (Rated Ambient Temperature)	Full power dissipation at 70° C and linearly de-rated to zero at + 225° C
Insulation	Not Insulated
Resistance Tolerance	± 5% (Available up to ± 1%)
Inductance	< 10 nH
Operating Temperature Range	- 55° C to +160° C
Voltage Rating / Limiting Voltage / Max. Working Voltage	√P x R
subject to max. terminal temperature + 120° C	
Temperature Co-efficient of Resistance	For – HOS2W & HOS3W 240ppm – For Resistance value < R004. 40ppm – For Resistance value R004 to R015 40ppm – For Resistance value > R015. For – HOS5W
[Measured from 0°C to +125°C]	240ppm – For Resistance value < R002. 40ppm – For Resistance value R002 to R007. 40ppm – For Resistance value > R007.
Thermal Shock	ΔR ± [0.75] – Average
Temperature Cycling [Room temperature →-55°C → Room temperature →125°C →	For – HOS2W & HOS3W $\Delta R \pm [<1.0~\%] - For Resistance value < R004.$ $\Delta R \pm [<1.0~\%] - For Resistance value R004 to R015.$ $\Delta R \pm [<0.75~\%] - For Resistance value > R015.$ For – HOS5W
Room temperature for 5 cycles]	$\Delta R \pm [<1.0~\%]$ – For Resistance value < R002. $\Delta R \pm [<1.0~\%]$ – For Resistance value R002 to R007. $\Delta R \pm [<0.75~\%]$ – For Resistance value > R007.
High Temp. Exposure (125°C- For 2 Hrs.)	For – HOS2W & HOS3W $\Delta R \pm [< 1.75 \%]$ – For Resistance value < R004. $\Delta R \pm [< 0.5 \%]$ – For Resistance value R004 to R015. $\Delta R \pm [< 1.0 \%]$ – For Resistance value > R015. For – HOS5W
righ temp. Exposure (125 C-FOI 2 HIS.)	$\Delta R \pm [< 1.75 \%]$ – For Resistance value < R002. $\Delta R \pm [< 0.5 \%]$ – For Resistance value R002 to R007. $\Delta R \pm [< 1.0 \%]$ – For Resistance value > R007.
Damp Heat (Steady State) (40°C at 93 % R.H. for 1000 Hrs. – no load applied)	ΔR ± [0.5 %] – Average
Endurance – Load Life [70°C with limiting voltage –	For – HOS2W & HOS3W $\Delta R \pm [<2.0~\%] - For Resistance value < R004.$ $\Delta R \pm [<1.0~\%] - For Resistance value R004 to R015.$ $\Delta R \pm [<1.0~\%] - For Resistance value > R015.$ For – HOS5W
with temperature limitation on terminal kept at 120°C 1.5 hours on / 0.5 hours off for 1000 hours]	$\Delta R \pm [< 2.0 \%]$ – For Resistance value < R002. $\Delta R \pm [< 1.0 \%]$ – For Resistance value R002 to R007. $\Delta R \pm [< 1.0 \%]$ – For Resistance value > R007.
Bias Humidity [+85° C, 85% RH, 1000h]	$\Delta R \pm 0.5\%$ - Typical
Mechanical Shock [100 g. 6 ms half sine]	$\Delta R \pm 0.5\%$ - Typical
Vibration, High Frequency [20 g. 10-2000 Hz]	$\Delta R \pm 0.5\%$ - Typical
Low Temperature Storage and Operation [-65° C for 24 h]	$\Delta R \pm 0.2\%$ - Typical
Moisture Resistance [MIL-STD-202 method106]	$\Delta R \pm 0.2\%$ - Typical

HOT SPOT TEMPERATURE RISE (IN STILL AIR) -

From 180 °C to 280 °C at 100% power depending on the resistance value, pad and PCB thickness. Due to the nature of it's construction, the HOS resistor keeps the hot spot from a thermal point of view from the solder joints and reduces the possibility of transfer of high temperature on to the PCB in contrast to the flat chip format.

SOLDER JOINT TEMPERATURE RISE (IN STILL AIR) -

From 60 °C to 85 °C at 100% power depending upon resistance value, pad and PCB thickness.

CONSTRUCTION:

The copper terminals are electron beam welded to the requisite alloy strip and then formed. Value variations are possible by variations of width without traditional abrasion / notch trimming.



MECHANICAL SPECIFICATIONS

PARAMETER / PERFORMANCE TEST & TEST METHOD	PERFORMANCE REQUIREMENTS
Resistance to Soldering heat - (350° C for 30 Secs)	Δ R \pm [0.2 %] – Typical
Solderabillity (Meets J-STD-002 Method B)	Must meet the requirements laid down
Solvent Resistance (Meets MIL-STD-002 Method 215)	Must meet the requirements laid down



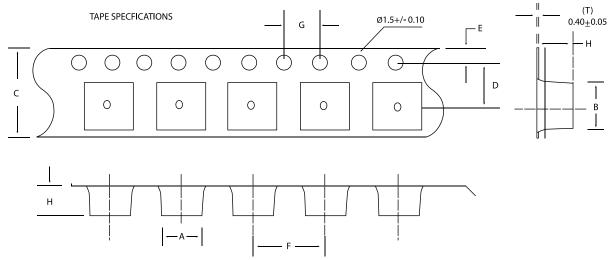
RECOMMENDED SOLDER PROFILE

Reflow, IR - and wave soldering								
Temperature (°C)	260	255	217					
Time (Sec)	Peak	40	90					

PACKAGING

A. BULK

B. TAPE & REEL PACKING



DIMENSIONAL TABLE

Sr No.	HTRTYPE	A(MM)	B(MM)	C(MM)	D(MM)	E(MM)	F(MM)	G(MM)	H(MM)	PCS/REEL
1	HOS2W & HOS3W ≥ R003	4.32±0.1	11.7±0.1	24±0.3	11.5±0.1	1.75±0.1	8.0±0.1	4.0±0.1	4.5±0.1	2000 pcs.
2	HOS2W & HOS3W R002	4.32±0.1	12.1±0.1	24±0.3	11.5±0.1	1.75±0.1	8.0±0.1	4.0±0.1	4.5±0.1	1750 pcs.
3	HOS5W R001 to R025	7.21±0.1	12.1±0.1	24±0.3	11.5±0.1	1.75±0.1	12.0±0.1	4.0±0.1	4.5±0.1	1250 pcs.

Storage Condition (Packed) : Temp 25° C to 35° C, Humidity 30 to 80% RH, Shelf life-12 months Floor Life (Unpacked) : Temp 25° C to 35° C, Humidity 30 to 80% RH, Floor life-15 days

ORDERING INFORMATION

Series	HTR Part No.	Туре	Resistance Value	Tolerance	Marking on Resistor
HOS	HOS5W	Bulk-HOS5W	R025	±1%	HTR R025 F
HOS	HOS5W	Tape & Reel –HOS5WTR	R025	±5%	HTR R025 J

Part no. of HOS5W, bulk with Resistance value, R025 and 1% tolerance will be **HOS5W R025 1%**Part no. of HOS5W, Tape & reel with Resistance value, R025 and 5% tolerance will be **HOS5WTR R025 5%**